S3A THRU S3M

SURFACE MOUNT GLASS PASSIVATED SILICON RECTIFIER

REVERSE VOLTAGE: FORWARD CURRENT:

50 to 1000 VOLTS 3.0 AMPERE

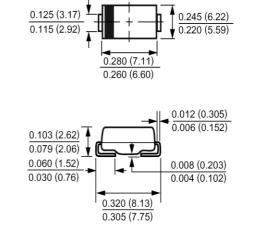
http://www.njzrg.com

FEATURES

- \cdot For surface mounted applications
- · Low profile package
- · Built-in strain relief
- · Easy pick and place
- · Low forward voltage drop
- · Plastic package has Underwriters Laboratory
- Flammability Classification 94V-O
- \cdot High temperature soldering : 260°C /10 seconds at terminals

MECHANICAL DATA

Case: Molded plastic, DO-214AB(SMC) Terminals: Solder plated, solderable per MIL-STD-750, method 2026 guaranteed Polarity: Color band denotes cathode end Packaging: 16mm tape per EIA STD RS-481 Weight: 0.007 ounce, 0.21 gram



DO-214AB(SMC)

Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25 ambient temperature unless otherwise specified. Single phase, half wave, $60H_Z$, resistive or inductive load. For capacitive load, derate current by 20%.

	Symbols	S3A	S3B	S3D	S3G	S3J	S3K	S3M	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current at T _L =75	I _(AV)	3.0							Amp
Peak Forward Surge Current,									
8.3ms single half-sine-wave	I _{FSM}	I _{FSM} 100							Amp
superimposed on rated load (JEDEC method)									
Maximum Forward Voltage at 3.0A	V _F	1.15							Volts
Maximum Reverse Current at T _A =25	т	10.0 250							μАтр
at Rated DC Blocking Voltage T _A =125	I _R								
Typical Junction Capacitance (Note 1)	CJ	53							pF
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	ја 47							
	$\mathbf{R}_{\theta JL}$				13				/W
Maximum Reverse Recovery Time (Note 3)	T _{RR}	2.5							μS
Operating Junction Temperature Range	T _J	-55 to +150							
Storage Temperature Range	Tstg				-55 to +15	0			

NOTES:

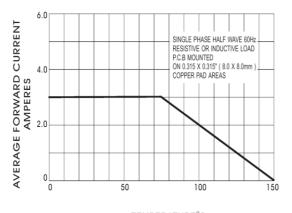
1- Measured at 1 MH_z and applied reverse voltage of 4.0 VDC.

2- Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.3 x 0.3" (8.0 x 8.0mm) copper pad areas

3- Reverse Recovery Test Conditions : $I_{F} {=} .5 A$, $I_{R} {=} 1 A$, $I_{RR} {=} .25 A.$

GROWCHILD ELECTRONICS^{TV}

RATINGS AND CHARACTERISTIC CURVES



TEMPERATURE°C Fig. 1- DERATING CURVE FOR OUTPUT RECTIFIED CURRENT

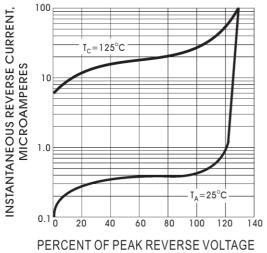
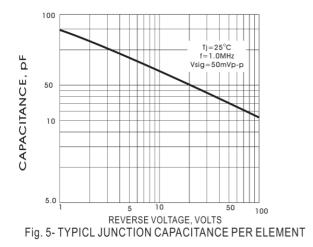
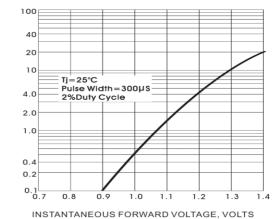


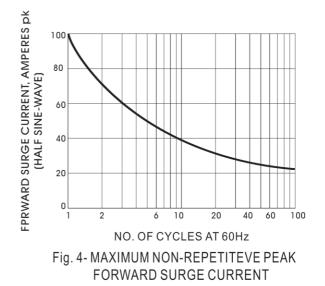
Fig. 3- TYPICAL REAK REVERSE CHARACTERISTICS





INSTANTANEOUS FORWARD CURRENT, AMPERES

Fig. 2- TYPICAL INSTANTANEOUS FORWARD CHARACTERISITCS PER ELEMENT



GROWCHILD

http://www.njzrg.com